ABSTRACT OF THE DISCLOSURE

An apparatus for processing a microelectronic workpiece is set forth. The apparatus comprises a workpiece support adapted to hold the microelectronic workpiece and a processing container adapted to receive the microelectronic workpiece held by the workpiece support. A drive mechanism is connected to drive the processing container and the workpiece support holding the microelectronic workpiece relative to one another so that the microelectronic workpiece may be moved to a plurality of workpiece processing positions. At least two chemical delivery systems are employed. A first chemical delivery system is used to provide at least one processing fluid to the processing container for application to the microelectronic workpiece when the microelectronic workpiece is in a first one of the plurality of workpiece processing positions while a second chemical delivery system is used to provide at least one processing fluid to the processing container for application to the microelectronic workpiece when the microelectronic workpiece is in a second one of the plurality of microelectronic workpiece processing positions. The apparatus also includes at least two chemical collector systems. A first chemical collector system is used to assist in at least partially removing spent processing fluid provided by the first chemical delivery system while the microelectronic workpiece is in the first one of the plurality of workpiece processing positions. Similarly, a second chemical collector system is used to assist in at least partially removing spent processing fluid provided by the second chemical delivery system from the processing

container while the microelectronic workpiece is in the second one of the plurality of microelectronic workpiece processing positions. In accordance with one embodiment, the apparatus is particularly adapted to execute an immersion process, such as electroplating, and a spraying process, such as an in-situ rinse.